L Number	Hits	Search Text	DB	Time stamp
1	1564	29/603.07,603.11,603.13-603.17,417.ccls.	USPAT; JPO; DERWENT	2004/05/26 11:41
2	3493	360/121,123,126,317,235.7,235.8,236.3,236.5,236.6,237.ccls.	USPAT; JPO; DERWENT	2004/05/26 11:42
3	3998	wafer with (slider or transducer or (magnetic adj head))	USPAT; JPO; DERWENT	2004/05/26 13:00
4	1141	wafer with metalliz$4	USPAT; JPO; DERWENT	2004/05/26 11:43
5	43	(wafer with (slider or transducer or (magnetic adj head))) and (wafer with metalliz$4)	USPAT; JPO; DERWENT	2004/05/26 11:43
6	2285	wafer with (slider or (magnetic adj head))	USPAT; JPO; DERWENT	2004/05/26 11:56
7	3	(wafer with metalliz$4) and (wafer with (slider or (magnetic adj head)))	USPAT; JPO; DERWENT	2004/05/26 12:02
8	6	slider with (solder adj bond$3)	USPAT; JPO; DERWENT	2004/05/26 12:10
9	12	5821494.URPN.	USPAT	2004/05/26 12:02
10	20	("3463898" | "4761699" | "4789914" | "4893742" | "4970365" | "4996623" | "5001583" | "5124277" | "5172851" | "5177860" | "5187623" | "5193738" | "5298715" | "5299729" | "5327310" | "5366692" | "5384090" | "5530604" | "5680275" | "5699212").PN.	USPAT	2004/05/26 12:04
12	1	(slider or transducer) with (solder adj bond$3) with (suspension or flexure)	USPAT; JPO; DERWENT	2004/05/26 12:06
11	29	(slider or transducer) with (solder adj bond$3)	USPAT; JPO; DERWENT	2004/05/26 12:10
13	240	360/121,123,126,317,235.7,235.8,236.3,236.5,236.6,237.ccls. and (wafer with (slider or (magnetic adj head)))	USPAT; JPO; DERWENT	2004/05/26 12:10
15	1	(360/121,123,126,317,235.7,235.8,236.3,236.5,236.6,237.ccls. and (wafer with (slider or (magnetic adj head)))) and ((suspension or flexure) and (solder adj bond$3))	USPAT; JPO; DERWENT	2004/05/26 12:14
16	15	5806524.URPN.	USPAT	2004/05/26 12:12
17	7	("4670804" | "4819094" | "4996623" | "5001583" | "5006946" | "5140482" | "5335126").PN.	USPAT	2004/05/26 12:13
18	47288	(lead$3 adj edge) and (trail$3 adj edge)	USPAT; JPO; DERWENT	2004/05/26 12:15
19	191	(wafer with (slider or transducer or (magnetic adj head))) and ((lead$3 adj edge) and (trail$3 adj edge))	USPAT; JPO; DERWENT	2004/05/26 12:15
20	799	((lead$3 adj edge) and (trail$3 adj edge)) with slider	USPAT; JPO; DERWENT	2004/05/26 12:15
21	2	(((lead$3 adj edge) and (trail$3 adj edge)) with slider) and (solder adj bond$3)	USPAT; JPO; DERWENT	2004/05/26 12:16
22	100	slider same (suspension or flexure) same solder	USPAT; JPO; DERWENT	2004/05/26 12:17
23	13	(((lead$3 adj edge) and (trail$3 adj edge)) with slider) and (slider same (suspension or flexure) same solder)	USPAT; JPO; DERWENT	2004/05/26 12:43
24	12	("4594221" | "4700250" | "4732733" | "4866836" | "4996623" | "5026434" | "5145553" | "5331489" | "5334346" | "5424030" | "5427848" | "6282064").PN.	USPAT	2004/05/26 12:18

25	117	29/840.ccls. and (solder adj bond$3)	USPAT; JPO; DERWENT	2004/05/26 12:51
26	0	(29/840.ccls. and (solder adj bond$3)) and (wafer with (slider or (magnetic adj head)))	USPAT; JPO; DERWENT	2004/05/26 12:44
27	0	(29/840.ccls. and (solder adj bond$3)) and (wafer with (slider or transducer or (magnetic adj head)))	USPAT; JPO; DERWENT	2004/05/26 12:44
28	678	228/$.ccls. and (solder adj bond$3)	USPAT; JPO; DERWENT	2004/05/26 13:00
29	1	(wafer with (slider or transducer or (magnetic adj head))) and (228/$.ccls. and (solder adj bond$3))	USPAT; JPO; DERWENT	2004/05/26 12:51
14	224	(suspension or flexure) and (solder adj bond$3)	USPAT; JPO; DERWENT	2004/05/26 13:00
30	982	228/180.22,1115.2.ccls.	USPAT; JPO; DERWENT	2004/05/26 13:00
31	157	228/180.22,1115.2.ccls. and (solder adj bond$3)	USPAT; JPO; DERWENT	2004/05/26 13:00
32	4	(228/180.22,1115.2.ccls. and (solder adj bond$3)) and (slider or transducer or (magnetic adj head))	USPAT; JPO; DERWENT	2004/05/26 13:01